

Product Name: ZX050C-MSOP8 (TSSOP8) MSOP8-EP (TSSOP8) Characterization testing bringup breakout module

Product Description: High Speed characterization module meeting 10GHz signal bandwidth with < 0.3dB insertion loss. Each pin of the device under test- DUT, U1, is accessible via 2 dedicated SMA connectors for external stimulus as well as measurement purpose.

ZX050C-MSOP8 (TSSOP8) is designed for ASIC Integrated Circuit (IC) characterization, functional testing of ANY MSOP8 (TSSOP8) packaged. ZX50C-MSOP8 is designed with 50 Ω (Ohms) trace impedance using 4 layer PCB. The module includes 35μ gold plated SMA connectors.

Ideal evaluation, bringup, and testing of any discrete component such as ESD diode using MSOP8 (TSSOP8) footprint package.

Available 2 pin header for interfacing to any standard Power Supply. The onboard C1 (0402 SMD package) is available for applications using pin 5 of the DUT as supply rail to the device. C1 can be populated with 0.1 μF or similar decoupling capacitor.

AGND pin of the 2 pin header is the module's GND reference, interfacing with the module's AGND layers.

The "7-GND" SMA connectors have connection option to the module's GND reference, AGND, via onboard SS2 , SS3 (0402 SMD package). The SS2, SS3 can be removed, if required.

- Application:** Bringup, Characterization, testing, development, design evaluations
- Target DUT :** Designed specifically for any MSOP8 TSSOP8 MSOP8-EP SMD device with SMA connector access to all pins of the MSOP8 device.
- Pitch:** Standard MSOP8 MSOP8-EP (exposed pad) TSSOP8 SMD package or equivalent
- Headers:** Ground access test point (GND) - 0.025" SQ with 0.32" (5.6mm) post height

DUT landing with EXPOSED Pad, EP: Two 0603 SMD devices are reserved connecting the EP to GND.

DUT landing pads: Surface Mount, 8 pin package – see table below

MSOP8 DIMENSIONS (mm)

UNIT		E	E1	e	D	b
mm	max	5.10	3.10	0.65	3.100	0.40
	Typical min					

TSSOP8 DIMENSIONS (mm)

UNIT		E	E1	e	D	b
mm	max	5.10	3.10	0.65	3.100	0.38
	Typical min					

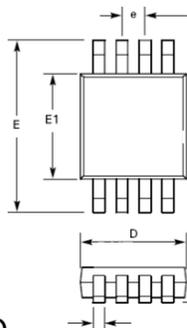
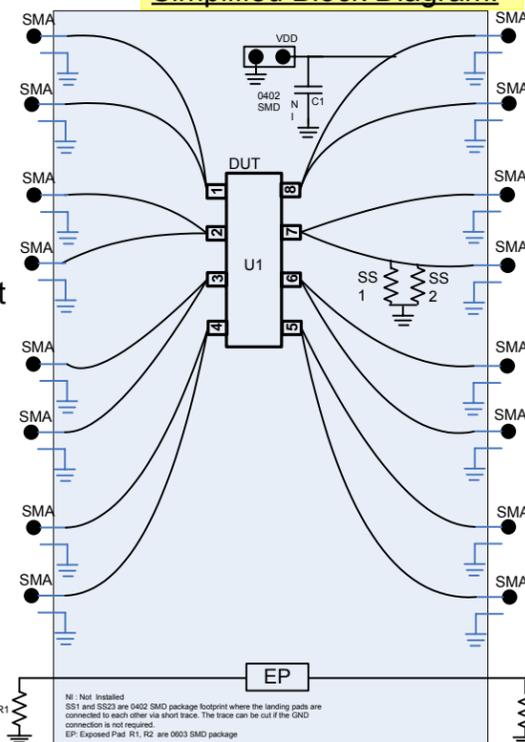
OUTLINE Version	REFERENCES		
	IEC	JEDEC	JEITA
SOT505-1		MO-187 AA	
SOT505-2		MO-187 AA	

Notice

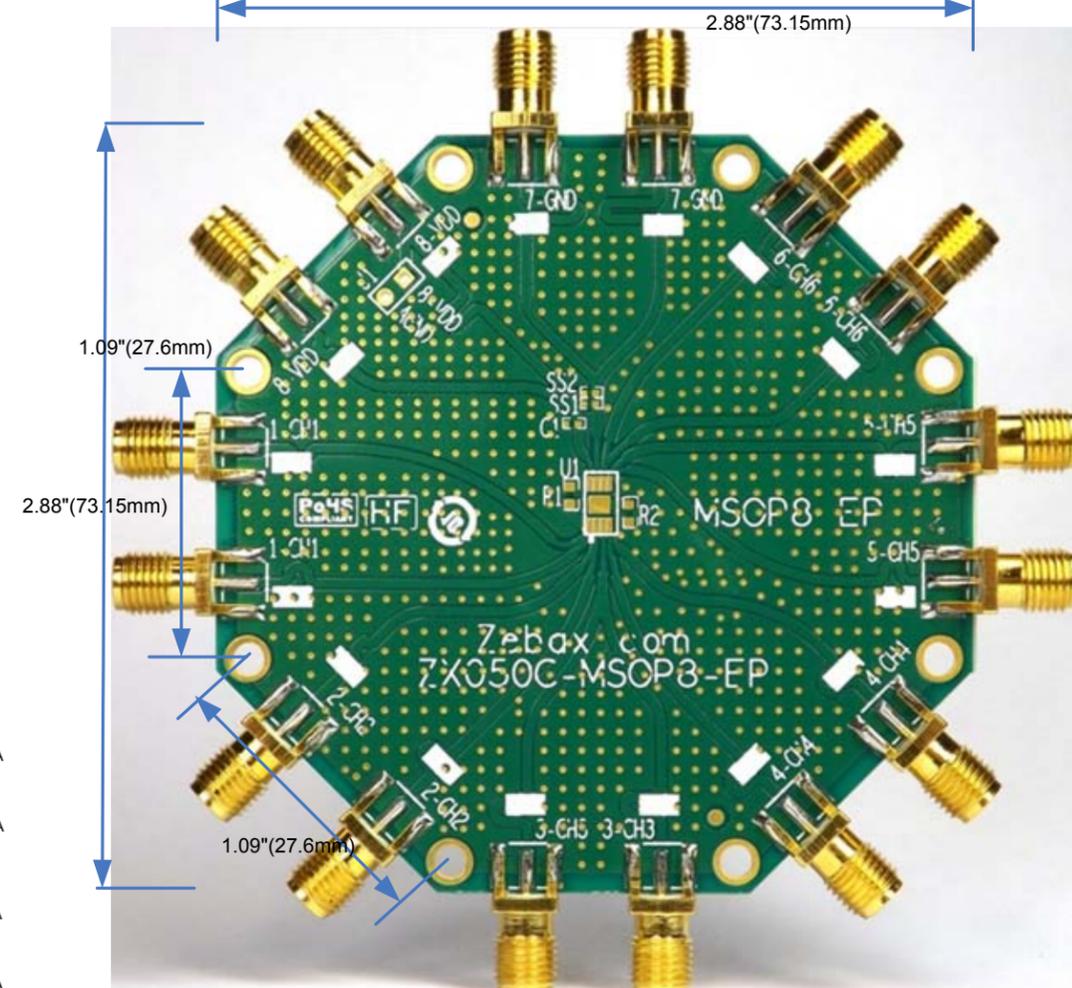
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Simplified Block Diagram:



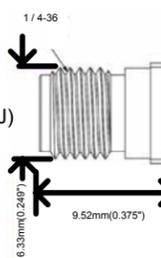
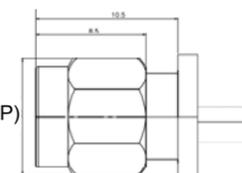
- SMA:**
 - Impedance: 50Ω
 - Temp Range: -65°C +165°C
 - Vibration: MIL-STD-202, Method 213
 - Frequency Range: DC – 12GHz
 - Working Voltage: 335V max
 - Withstand Voltage: 1000V rms
 - Center Contact: ≤3mΩ
 - Outer Contact: ≤2mΩ
 - Insulation resistance: ≥5000MΩ
 - VSWR Straight: ≤1.15 (0.8-2.5G)



Ordering INFO:

- Part Number
- ZX050C-MSOP8-J SMA Jack Connector type (standard)
- ZX050C-MSOP8-P SMA Plug connector type

NOTE: ZX050C-MSOP8 is shipped without DUT and C1. All SMA connectors are installed.



Note
ALL ZEBAX products are RoHS compliant and Lead Free unless otherwise indicated.

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ASSEMBLY DRAWING
ITEM: ZX050C-MSOP8-TSSOP8

DESCRIPTION: MSOP8 (TSSOP8) characterization testing bringup breakout adapter SMA

CHECKED: M. MARINA DRAWN: SLAVIK REVISION: 1.0
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